

	Hits	Search Text	DBs
1	1	("20050211464").PN.	US-PGPUB; USPAT; USOCR
2	124889	"156"/\$7.ccls.	US-PGPUB; USPAT; USOCR
3	76943	anisotropic or anisotropical\$2	US-PGPUB; USPAT; USOCR
4	898693	adhesive or glue or binder	US-PGPUB; USPAT; USOCR
5	222785	circuit adj (board or substrate) or microcircuit	US-PGPUB; USPAT; USOCR
6	122	S2 and S3 with S4 and S5	US-PGPUB; USPAT; USOCR
7	5	("5720843" "6020059" "6034331" "6172878" "6365840").PN. OR ("6835274").URPN.	US-PGPUB; USPAT; USOCR
8	1	("5800650").PN.	US-PGPUB; USPAT; USOCR

	Hits	Search Text	DBs
9	125	("2808352" "3148310" "3181209" "3205299" "3320658" "3334040" "3359145" "3421961" "3475213" "3491056" "3532570" "3541222" "3622384" "3644166" "3680037" "3774232" "3795047" "3823252" "3853691" "3883213" "3885173" "3904934" "3971610" "3982320" "3984598" "3990926" "3998601" "4037047" "4064357" "4064622" "4064623" "4065197" "4073699" "4088544" "4091138" "4109377" "4113576" "4113981" "4169018" "4193849" "4261042" "4357395" "4383003" "4407685" "4410388" "4457796" "4508399" "4508990" "4511757" "4529477" "4554033" "4568413" "4581679" "4608274" "4610756" "4628022" "4629681" "4642160" "4645552" "4659872" "4670325" "4690833" "4713494" "4729809" "4735847" "4744850" "4747211" "4771537" "4778635" "4788766" "4800461" "4808435" "4810528" "4812213" "4814040" "4873123" "4908940" "4926549" "4928206" "4945029" "4959246" "4980034"	US-PGPUB; USPAT; USOCR

		"5004639" "5041183" "5044053" "5046238" "5072074" "5080929" "5084961" "5095628" "5102343" "5112462" "5121297" "5133120" "5137791" "5175047" "5359767" "5502889").PN. OR ("5800650").URPN.	
10	16511	coverlayer or cover adj layer	US-PGPUB; USPAT; USOCR
11	130	S3 and S5 and S10	US-PGPUB; USPAT; USOCR
12	109149	polyimide	US-PGPUB; USPAT; USOCR

	Hits	Search Text	DBs
13	283366	epoxy	US-PGPUB; USPAT; USOCR
14	222785	circuit adj (board or substrate) or microcircuit	US-PGPUB; USPAT; USOCR
15	16511	coverlayer or cover adj layer	US-PGPUB; USPAT; USOCR
16	29	S14 and S15 with S12 with S13	US-PGPUB; USPAT; USOCR
17	55	S14 and S15 same S12 with S13	US-PGPUB; USPAT; USOCR
18	26	S17 not S16	US-PGPUB; USPAT; USOCR
19	300	S14 and S15 same (S12 or S13)	US-PGPUB; USPAT; USOCR
20	245	S19 not S17	US-PGPUB; USPAT; USOCR
21	213225	circuit adj (board or substrate) or microcircuit	EPO; JPO; DERWENT; IBM_TDB
22	12950	coverlayer or cover adj layer	EPO; JPO; DERWENT; IBM_TDB
23	39119	anisotropic or anisotropical\$2	EPO; JPO; DERWENT; IBM_TDB
24	4	S23 and S24	EPO; JPO; DERWENT; IBM_TDB
25	257	S21 and S22	EPO; JPO; DERWENT; IBM_TDB
26	86406	(insulation or dielectric) adj (layer or coating)	EPO; JPO; DERWENT; IBM_TDB
27	15	S21 and S24 and S26	EPO; JPO; DERWENT; IBM_TDB
28	258151	thermoplastic	US-PGPUB; USPAT; USOCR
29	47202	softening adj point	US-PGPUB; USPAT; USOCR
30	15	S28 with S12 with S29	US-PGPUB; USPAT; USOCR
31	50	S28 with S13 with S29	US-PGPUB; USPAT; USOCR
32	5	S31 and S14	US-PGPUB; USPAT; USOCR
33	224	(S12 or S13) with S29 and S14	US-PGPUB; USPAT; USOCR
34	229	(S12 or S13 or polyamide) with S29 and S14	US-PGPUB; USPAT; USOCR
35	3	S15 and S34	US-PGPUB; USPAT; USOCR
36	119936	(insulation or dielectric) adj (layer or coating)	US-PGPUB; USPAT; USOCR

	Hits	Search Text	DBs
37	33	S34 and S36	US-PGPUB; USPAT; USOCR
38	196	S34 not S37	US-PGPUB; USPAT; USOCR
39	0	S28 with S15 with (S29 or S36) and S14	US-PGPUB; USPAT; USOCR
40	2	S15 same S29 and S14	US-PGPUB; USPAT; USOCR
41	39	S36 same S29 and S14	US-PGPUB; USPAT; USOCR
42	23838	softening adj point	EPO; JPO; DERWENT; IBM_TDB
43	28	S22 and S42	EPO; JPO; DERWENT; IBM_TDB
44	72	(epoxy or polyamide) and S21 and S42	EPO; JPO; DERWENT; IBM_TDB
45	42	(epoxy or polyamide) with S42 and S21	EPO; JPO; DERWENT; IBM_TDB